UNR92A3G

Silicon NPN epitaxial planar type

For digital circuits

Features

- Optimum for high-density mounting and downsizing of the equipment
- Contribute to low power consumption

Absolute Maximum Ratings $T_a = 25^{\circ}C$ Parameter Collector-base voltage (Emitter open) Collector-emitter voltage (Base open) Collector current Total power dissipation Junction temperature Storage temperature

SSMini3-F3
Pin Name
1: Base
2: Emitter
- 3: Collector
-
_ Marking Symbol: FN
- $or or o$

Package

Code

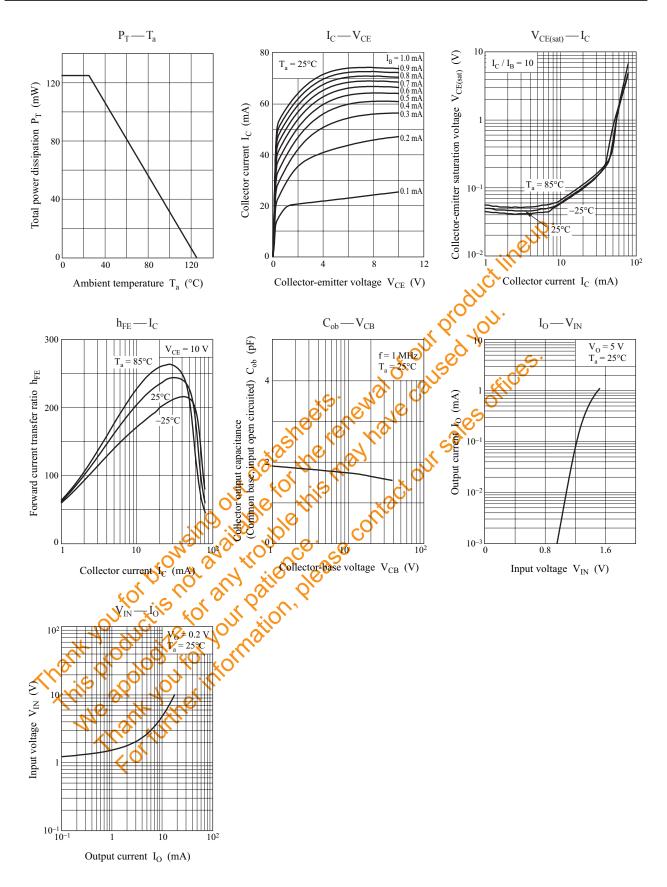
Electrical Characteristics

Parameter	Cumbol	Deting	Unit 3: C	Collector	\mathcal{N}		
	Symbol	Rating		, jor			
Collector-base voltage (Emitter open)	V _{CBO}	50	Ma	irking Syr	nbol: FN	1	
Collector-emitter voltage (Base open)	V _{CEO}	50	V Ó	, ₀ 0	•		
Collector current	I _C	80		ernal Con	nection		
Total power dissipation	P _T	125	V mA mW °C	₿œ—	R ₁ M	r ^o c	
Junction temperature	Tj	125	°C	Ś	$R_2 \ge$		
Storage temperature	T _{stg}	-55 to +125	S°C N S	0	- ²	••• E	
, C							
Electrical Characteristics $T_a = 2$	Soc Feed	outerole	3050				
Electrical Characteristics T _a =2 Parameter	C±20 Symbo	oul ce	°C ONTROLOUTS	Min	Тур	Max	Un
Electrical Characteristics T _a =2 Parameter Collector-base voltage (Emitter open)	C±200		$\frac{\text{Conditions}}{I_{\rm E}=0}$	Min 50	Тур	Max	
Electrical Characteristics T _a = 2 Parameter Collector-base voltage (Emitter open) Collector-emitter voltage (Base open)		$\frac{1}{C} = 10 \mu A$	$I_E = 0$	Min 50 50	Тур	Max	V
Collector-emitter voltage (Base open)		$\frac{1}{C} = 10 \mu A$ $\frac{1}{C} = 2 m A$ $\frac{1}{V_{CB}} = 50$	$, I_{\rm B} = 0$	Min 50 50	Тур	Max 0.1	Un V V
Collector-emitter voltage (Base open) Collector-base cutoff current (Emitter op	en) CBO	$I_{\rm C} = 2 \rm mA$	$I_{\rm B} = 0$ V, $I_{\rm E} = 0$	Min 50 50	Тур		V V
Collector-emitter-voltage (Base open) Collector-base cutoff current (Emitter op Collector-emitter cutoff current (Base op	en) Q _{CBO} en) I _{CEO}	$V_{CB} = 50$	$I_{\rm B} = 0$ V, $I_{\rm E} = 0$ V, $I_{\rm B} = 0$	Min 50 50	Тур	0.1	V V μ/
Collector-emitter voltage (Base open) Collector-base cutoff current (Emitter op Collector-emitter cutoff current (Base op Emitter-base cutoff current (Collector op	en) CEO	$I_{C} = 2 \text{ mA}$ $V_{CB} = 50 \text{ V}$ $V_{CE} = 50 \text{ V}$ $V_{EB} = 6 \text{ V},$	$I_{\rm B} = 0$ V, $I_{\rm E} = 0$ V, $I_{\rm B} = 0$	Min 50 50 	Тур	0.1	V V μ/
Collector-emitter voltage Base open) Collector-base cutoff current (Emitter op Collector-emitter cutoff current (Base op Emitter-base cutoff current (Collector op Forward current transfer ratio	en) I_{CEO} en) I_{EBO}		$I_{\rm B} = 0$ V, $I_{\rm E} = 0$ V, $I_{\rm B} = 0$ $I_{\rm C} = 0$	50	Тур	0.1	V V μ4 m4
Collector-emitter voltage (Base open) Collector-base cutoff current (Emitter op Collector-emitter cutoff current (Base or Emitter-base cutoff current (Collector op Forward current transfer ratio Collector-emitter saturation Voltage	$\begin{array}{c c} & & & \\ & & \\ & & \\ en \end{pmatrix} & & \\ \hline & & \\ I_{CEO} \\ en \end{pmatrix} & & \\ \hline & & \\ I_{EBO} \\ \hline & & \\ h_{FE} \end{array}$	$I_{C} = 2 \text{ mA}$ $V_{CB} = 50 \text{ V}$ $V_{CE} = 50 \text{ V}$ $V_{EB} = 6 \text{ V}$ $V_{CE} = 10 \text{ V}$ $I_{C} = 10 \text{ mA}$	$I_{\rm B} = 0$ $V, I_{\rm E} = 0$ $V, I_{\rm B} = 0$ $I_{\rm C} = 0$ $V, I_{\rm C} = 5 \text{ mA}$	50	Тур	0.1 0.5 0.1	V V μ4 mμ
Collector-emitter voltage (Base open) Collector-base cutoff current (Emitter op Collector-emitter cutoff current (Base op Emitter-base cutoff current (Collector op Forward current transfer ratio Collector-emitter saturation Voltage Dutput voltage high-level	en) Q_{CBO} en) I_{CEO} en) I_{EBO} h_{FE} $V_{CE(sat)}$	$I_{C} = 2 \text{ mA}$ $V_{CB} = 50 \text{ V}$ $V_{CE} = 50 \text{ V}$ $V_{EB} = 6 \text{ V}$ $V_{CE} = 10 \text{ M}$ $I_{C} = 10 \text{ mA}$ $V_{CC} = 5 \text{ V}$	$I_{\rm B} = 0$ $V, I_{\rm E} = 0$ $V, I_{\rm B} = 0$ $I_{\rm C} = 0$ $V, I_{\rm C} = 5 \text{ mA}$ $A, I_{\rm B} = 0.3 \text{ mA}$	80	Тур	0.1 0.5 0.1	V V μ4 m4
Collector-emitter voltage (Base open) Collector-base cutoff current (Emitter op Collector-emitter cutoff current (Base op Emitter-base cutoff current (Collector op Forward current transfer vatio Collector-emitter saturation coltage Output voltage high-level Output voltage low-level	en) I_{CBO} en) I_{CBO} en) I_{EBO} h_{FE} $V_{CE(sat}$ V_{OH}	$I_{C} = 2 \text{ mA}$ $V_{CB} = 50 \text{ V}$ $V_{CE} = 50 \text{ V}$ $V_{EB} = 6 \text{ V}$ $V_{CE} = 10 \text{ M}$ $I_{C} = 10 \text{ mA}$ $V_{CC} = 5 \text{ V}$	$I_{\rm B} = 0$ $V, I_{\rm E} = 0$ $V, I_{\rm B} = 0$ $I_{\rm C} = 0$ $V, I_{\rm C} = 5 \text{ mA}$ $A, I_{\rm B} = 0.3 \text{ mA}$ $V_{\rm B} = 0.5 \text{ V}, R_{\rm L} = 1 \text{ k}\Omega$	80	Тур 	0.1 0.5 0.1 0.25	V V μ4 μ4 Μ4 V V V V
Electrical Characteristics $T_a = 2$ Parameter Collector-base voltage (Emitter open) Collector-emitter voltage (Base open) Collector-base cutoff current (Emitter op Collector-emitter cutoff current (Base open) Collector-emitter cutoff current (Collector open) Forward current transfervatio Collector-emitter saturation voltage Output voltage high-level Output voltage low-level Input resistance Resistance ratio	en) V_{CBO} en) I_{CEO} en) I_{EBO} h_{FE} $V_{CE(sat)}$ V_{OH}	$I_{C} = 2 \text{ mA}$ $V_{CB} = 50 \text{ V}$ $V_{CE} = 50 \text{ V}$ $V_{EB} = 6 \text{ V}$ $V_{CE} = 10 \text{ m/}$ $I_{C} = 10 \text{ m/}$ $V_{CC} = 5 \text{ V}$	$I_{\rm B} = 0$ $V, I_{\rm E} = 0$ $V, I_{\rm B} = 0$ $I_{\rm C} = 0$ $V, I_{\rm C} = 5 \text{ mA}$ $A, I_{\rm B} = 0.3 \text{ mA}$ $V_{\rm B} = 0.5 \text{ V}, R_{\rm L} = 1 \text{ k}\Omega$	50 80 4.9		0.1 0.5 0.1 0.25	V V µA

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

UNR92A3G

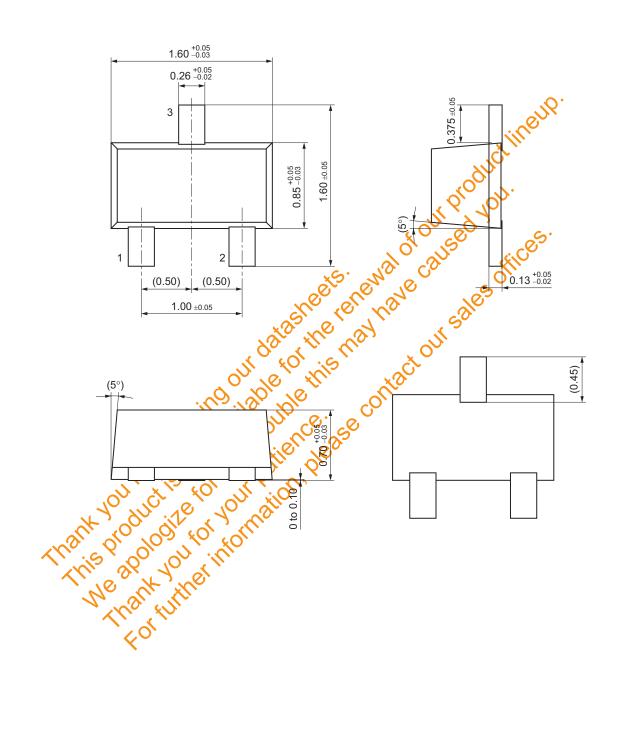
Panasonic



Panasonic

SSMini3-F3

Unit: mm



Request for your special attention and precautions in using the technical information and semiconductors described in this book

- (1) If any of the products or technical information described in this book is to be exported or provided to non-residents, the laws and regulations of the exporting country, especially, those with regard to security export control, must be observed.
- (2) The technical information described in this book is intended only to show the main characteristics and application circuit examples of the products, and no license is granted under any intellectual property right or other right owned by our company or any other company. Therefore, no responsibility is assumed by our company as to the infringement upon any such right owned by any other company which may arise as a result of the use of technical information described in this book.
- (3) The products described in this book are intended to be used for standard applications or general electronic equipment (such as office equipment, communications equipment, measuring instruments and household appliances).
 - Consult our sales staff in advance for information on the following applications:
 - · Special applications (such as for airplanes, aerospace, automobiles, traffic control equipment, combustion equipment, life support systems and safety devices) in which exceptional quality and reliability are required, or if the failure or malfunction of the products may directly jeopardize life or harm the human body.
 - Any applications other than the standard applications intended.
- (4) The products and product specifications described in this book are subject to change without notice to modification and/or improvement. At the final stage of your design, purchasing, or use of the products, therefore, ask for the most up-to-date Product Standards in advance to make sure that the latest specifications satisfy your requirements.
- (5) When designing your equipment, comply with the range of absolute maximum rating and the guaranteed operating conditions (operating power supply voltage and operating environment etc.). Especially, please be careful not exceed the range of absolute maximum rating on the transient state, such as power-on, power-off and mode-switching. Otherwise, we will not be liable for any defect which may arise later in your equipment.
 - Even when the products are used within the guaranteed values, take into the consideration of freak down and failure mode, possible to occur to semiconductor products. Measures on the system's such as build and design and the spread of fire or preventing glitch are recommended in order to prevent physical injury, tife, social damages, for example, by using the products.
- se, tak sures on the in physical spin. I provent breakdown and time of handling, rooming, i conditions, such as shell life and in reproduced whether wholly or particular the topological and the topological and the topological topological and the topological topological and the topologi (6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting on at customer's process. When using products for which damp-proof packing is required, satisfy the condition, such as helf life and the elapsed time since first opening the packages.
 - (7) This book may be not reprinted or reproduced whether wholls or partially, without the prior written permission of Matsushita Electric Industrial Co., Ltd.